J30J(MIL-DTL-83513 / MDM) Metal Shell 15pin Straight PCB Micro-D MIL-Spec Female Connector, 1.27x2.54mm Grid

Part Number:

J30J-15ZKN-J

Basic Information	
Connector Type	Receptacle
Orientation	Straight
Contact Type	Female
Number of Cores	15
Number of Interface Rows	2
Contact Spacing	1.27mm
Mounting Type	Panel Mount
Contact Termination	Solder
Color	Primary Color

Material Specification	
Housing Material	Aluminum Alloy
Housing Plating	Nickel-plated
Contacts Plating	Gold-plated

Electrical Specification	
Rated Current	3A
Withstand Dielectric Voltage	800V
Contact Resistance	≤ 10MΩ
Insulation Resistance	≥ 5000MΩ

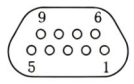
Environmental Specification	
Operating Temperature	-55℃ to +125℃

How to Order

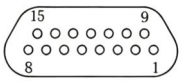
J30 — J — X- — X — TJ / ZK — X — X- — X

Code	Description	Options	
J30	Series / Basic Type	Micro-D Rectangular Connector (MIL-DTL-83513 Equivalent)	
J	Shell Material	**J** — Metal Shell	
X-	Series Modification	**Blank** — Basic Type **D** — M2-6H Mounting Holes **M1** — Glass Sintered Hermetic	**A** — Quick-lock **M** — Rubber Seal **S** — Stainless Steel Shell
X	Number of Contacts	9, 15, 21, 25, 31, 37, 51, 66, 69, 74, 100 pins	
TJ / ZK	Connector and Contact Type	**TJ** — Plug with Male Pins **ZK** — Receptacle with Female Sockets	
X	Termination Style	**Blank** — Crimp **N** — Straight PCB (Through-hole)	**S** — Solder Cup **W** — Right Angle PCB
X-	Locking Hardware Type	**K, L** — Free-end Locking Assembly **P, V** — Fixed-end Locking Assembly	
X	Modification Code	**A** — Shielding Sleeve (Crimp only) **D** — Anti-rotation Structure (Fixed-end only) **J** — 1.27mm × 2.54mm PCB Grid Spacing	**C** — Vertical Wire Exit (Crimp only) **AD** — Combination of A and D **Q, Q8** — Widened Flange

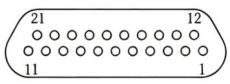
Contact Layout



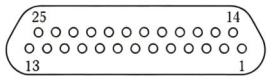
J30J-9 Pin



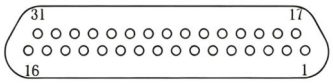
J30J-15 Pin



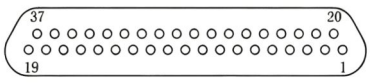
J30J-21 Pin



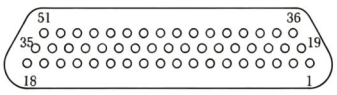
J30J-25 Pin



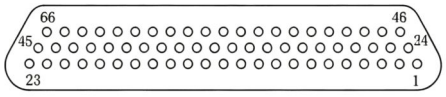
J30J-31 Pin



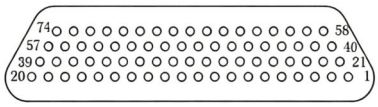
J30J-37 Pin



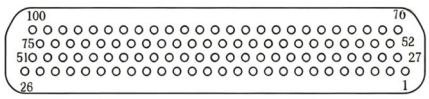
J30J-51 Pin



J30J-66 Pin



J30J-74 Pin



J30J-100 Pin

Disclaimer

The information in this specification is subject to change without notice. Please confirm the latest version before use. Technical parameters are for reference only, and sufficient testing and verification should be conducted in actual applications.